# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

# **CONVEYING PARTY DATA**

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HEE JOON LEE	12/11/2017	
JU-HYUN JI	12/11/2017	
CHUN HO PARK	12/11/2017	
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**PROPERTY NUMBERS Total: 1** 

PATENT REEL: 044399 FRAME: 0905

504688511

Property Type	Number
Application Number:	15842146

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DATE SIGNED:	12/14/2017

**Total Attachments: 3** 

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> PATENT REEL: 044399 FRAME: 0906

## COMBINED DECLARATION AND ASSIGNMENT FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

I believe I am the original or an original joint inventor of a claimed invention in the application for which a patent is sought on the invention entitled:

POLY	PROPYLENE RES	IN COMPOSITIC	N AND	MOLDED	PRODUCT	THEREOF
***************************************	***************************************	·····································		AND THE PERSON OF THE PERSON O		
which a	application is:					
$\boxtimes$	attached, or					
	United States applic	ation number or P	CT inten	national app	lication	
The abo	ove-identified applica	ition was made or	authorize	ed to be mad	le by me.	

In the event that the filing date and/or application number are not entered above at the time I execute this document, and if such information is deemed necessary, I hereby authorize and request the registered practitioners of McDermott Will & Emery LLP, associated with the Customer Number 20277, to insert above the filing date and/or application number of the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

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**REEL: 044399 FRAME: 0907** 

## ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I hereby assign to

Hyundai Motor Company and Kia Motors Corporation and LG Hausys, Ltd. and DAE HA CO.,LTD.

having an address 12, Heolleung-ro, Seocho-gu, Seoul, 06797, Republic of Korea and 12, Heolleung-ro, Seocho-gu, Seoul, 06797, Republic of Korea and 10, Gukjegeumyungro, Yeongdeungpo-gu, Seoul, 07326, Republic of Korea and 773, Sunscong-ro, Sunscongmyeon, Dangjin-si, Chungcheongnam-do, 31758, Republic of Korea, respectively (hereinafter designated as the Assignee), the entire (100%) right, title and interest for the United States as defined in 35 USC §100, in the invention described in the application identified in this document.

I hereby confirm any prior assignment to Assignee, and to the extent that I have not already done so, agree to assign, and hereby do, sell, assign and transfer unto Assignee and its successors in interest, the full and exclusive right, title and interest in the United States of America and throughout the world, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, to the inventions as described in the aforesaid application, to the aforesaid application itself, and all divisions, continuations, continuations-in-part, or other applications claiming priority directly or indirectly from the aforesaid application, and any United States or foreign Letters Patent, utility model, or other similar rights which may be granted thereon, including reissues, reexaminations and extensions thereof, and all copyright rights throughout the world in the aforesaid application and the subject matter disclosed therein, these rights, title and interest to be held and enjoyed by Assignee to the full end of the term for which the Letters Patent, utility model, or other similar rights, are granted and any extensions thereof as fully and entirely as the same would have been held by the undersigned had this assignment and sale not been made, and the right to sue for, and recover for past infringements of, or liabilities for, any of the rights relating to any of the applications, patents, utility models, or other similar rights, resulting therefrom, and the copyright rights;

I hereby covenant and agree to execute all instruments or documents required or requested for the making and prosecution of any applications of any type for patent, utility model, or other similar rights, and for copyright, in the United States and in all foreign countries including, but not limited to, any provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, and as to letters patent any reissue, re-examination, or extension thereof, and for litigation regarding, or for the purpose of protecting title and to the said invention, the United States application for patent, or Letters Patent therefor, and to testify in support thereof, for the benefit of Assignee without further or other compensation than that above set forth:

I hereby covenant that no assignment, sale, license, agreement or encumbrance has been or will be entered into which would conflict with this Assignment.

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REEL: 044399 FRAME: 0908

Legal name of first inventor	**************************************	
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First inventor's signature	Date	
Cim Hyin Gyung	December 11, 2017	
` <b>v</b>	***************************************	
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Second inventor's signature	Date	
LEE, HEE JOON	December 11, 2017	
Legal name of third inventor, if any		
JI, Ju-Hyun	**************************************	
Third inventor's signature	Date	
JI. Ju-Hyun	December 11, 2017	
(	ANNO METALISMENT DE L'ANNO METALISMENT DE L'ANNO METALISMENT DE L'ANNO METALISMENT DE L'ANNO METALISMENT DE L'A	
Legal name of fourth inventor, if any		
PARK, Chun Ho	T Date	
Fourth inventor's signature	1	
Park Chun Ho December 11, 2		
Legal name of fifth inventor, if any SUNG, Ki Hyun		
Fifth inventor's signature	Date	
Sung Ki Hyun	December 11, 2017	
Legal name of sixth inventor, if any	1.11.11.12.12.11.12.12.12.12.12.12.14.14.14.14.14.14.14.14.14.14.14.14.14.	
RYU, Kwan Suk	вуго <del>секто</del> оринемунияния пистем правинентини принцип <b>исминимали</b>	
Sixth inventor's signature	Date	
RYU, KUMIN TAIR SUK	December 11, 2017	